

SNx4ACT11 Triple 3-Input Positive-and Gates

1 Features

- 4.5V to 5.5V V_{CC} operation
- Inputs accept voltages to 5.5V
- Max t_{pd} of 10.5ns at 5V
- Inputs are TTL-voltage compatible

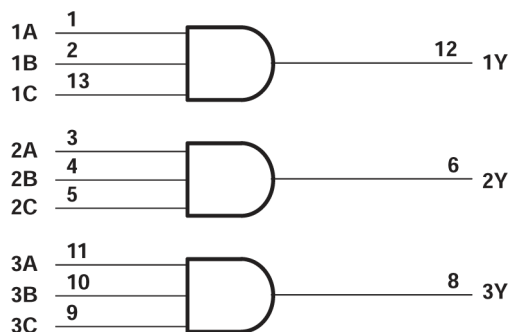
2 Description

The 'ACT11 devices contain three independent 3-input AND gates. These devices perform the Boolean function $Y = A \cdot B \cdot C$ or $Y = \overline{A} + \overline{B} + \overline{C}$ in positive logic.

Device Information

| PART NUMBER | PACKAGE ⁽¹⁾ | PACKAGE SIZE ⁽²⁾ | BODY SIZE ⁽³⁾ |
|-------------|------------------------|-----------------------------|--------------------------|
| SNx4ACT11 | DB (SSOP, 14) | 6.2mm x 7.8mm | 6.2mm x 5.3mm |
| | D (SOIC, 14) | 8.65mm x 6mm | 8.65 mm x 3.9mm |
| | N (PDIP, 14) | 19.3mm x 9.4mm | 19.3mm x 6.3 mm |
| | PW (TSSOP, 14) | 5mm x 6.4mm | 5mm x 4.4mm |
| | W (CFP, 14) | 9.21mm x 9mm | 9.21mm x 6.28mm |
| | FK, (LCCC, 14) | 8.9mm x 8.9mm | 8.9mm x 8.9mm |

- (1) For more information, see [Section 10](#).
- (2) The package size (length x width) is a nominal value and includes pins, where applicable.
- (3) The body size (length x width) is a nominal value and does not include pins.



Logic Diagram, Each Gate (Positive Logic)



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3 Pin Configuration and Functions

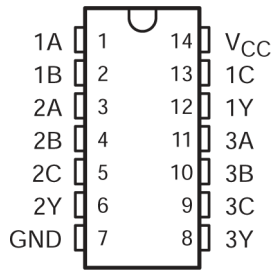
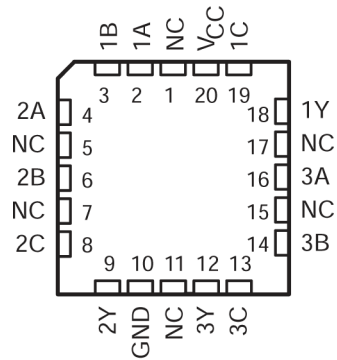


Figure 3-1. SN54ACT11 W Package; SN74ACT11 D, DB, N, or PW Package (Top View)



NC – No internal connection

Figure 3-2. SN54ACT11 FK Package (Top View)

| PIN | | I/O | DESCRIPTION |
|-----------------|-----|--------|---------------------|
| NAME | NO. | | |
| 1A | 1 | Input | Channel 1, Input A |
| 1B | 2 | Input | Channel 1, Input B |
| 2A | 3 | Input | Channel 2, Input A |
| 2B | 4 | Input | Channel 2, Input B |
| 2C | 5 | Input | Channel 2, Input C |
| 2Y | 6 | Output | Channel 2, Output Y |
| GND | 7 | — | Ground |
| 3Y | 8 | Output | Channel 3, Output Y |
| 3C | 9 | Input | Channel 3, Input A |
| 3B | 10 | Input | Channel 3, Input B |
| 3A | 11 | Input | Channel 3, Input C |
| 1Y | 12 | Output | Channel 1, Output Y |
| 1C | 13 | Input | Channel 1, Input C |
| V _{CC} | 14 | — | Positive Supply |

4 Specifications

4.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | MIN | MAX | UNIT |
|-------------------------------|---|---|-----------------------|------|
| V _{CC} | Supply voltage range | -0.5 | 7 | V |
| V _I ⁽²⁾ | Input voltage range | -0.5 | V _{CC} + 0.5 | V |
| V _O ⁽²⁾ | Output voltage range | -0.5 | V _{CC} + 0.5 | V |
| I _{IK} | Input clamp current | (V _I < 0 or V _I > V _{CC}) | | ±20 |
| I _{OK} | Output clamp current | (V _O < 0 or V _O > V _{CC}) | | ±20 |
| I _O | Continuous output current | (V _O = 0 or V _{CC}) | | ±50 |
| | Continuous current through V _{CC} or GND | | ±200 | mA |
| T _{stg} | Storage temperature range | -65 | 150 | °C |

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

4.2 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

| | | SN54ACT11 | | SN74ACT11 | | UNIT |
|-----------------|------------------------------------|-----------|-----------------|-----------|-----------------|------|
| | | MIN | MAX | MIN | MAX | |
| V _{CC} | Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V _{IH} | High-level input voltage | 2 | | 2 | | V |
| V _{IL} | Low-level input voltage | | 0.8 | | 0.8 | V |
| V _I | Input voltage | 0 | V _{CC} | 0 | V _{CC} | V |
| V _O | Output voltage | 0 | V _{CC} | 0 | V _{CC} | V |
| I _{OH} | High-level output current | | -24 | | -24 | mA |
| I _{OL} | Low-level output current | | 24 | | 24 | mA |
| Δt/Δv | Input transition rise or fall rate | | 8 | | 8 | ns/V |
| T _A | Operating free-air temperature | -55 | 125 | -40 | 85 | °C |

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

4.3 Thermal Information

| THERMAL METRIC ⁽¹⁾ | | SNx4ACT11 | | | | | UNIT |
|-------------------------------|--|-----------|-----------|----------|----------|------------|------|
| | | D (SOIC) | DB (SSOP) | N (PDIP) | NS (SOP) | PW (TSSOP) | |
| | | 14 PINS | 14 PINS | 14 PINS | 14 PINS | 14 PINS | |
| R _{θJA} | Junction-to-ambient thermal resistance | 119.9 | 96 | 80 | 76 | 145.7 | °C/W |

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

4.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | SN54ACT11 | | SN74ACT11 | | UNIT |
|---|--|-----------------|-----------------------|-------|------|-----------|------|-----------|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | I _{OH} = -50 μA | 4.5V | 4.4 | 4.49 | | 4.4 | | 4.4 | V | |
| | | 5.5V | 5.4 | 5.49 | | 5.4 | | 5.4 | | |
| | I _{OH} = -24 mA | 4.5V | 3.86 | | | 3.7 | | 3.76 | | |
| | | 5.5V | 4.86 | | | 4.7 | | 4.76 | | |
| | I _{OH} = -50 mA ⁽¹⁾ | 5.5V | | | | 3.85 | | | | |
| I _{OH} = -75 mA ⁽¹⁾ | 5.5V | | | | | | 3.85 | | | |
| V _{OL} | I _{OL} = 50 μA | 4.5V | | 0.001 | 0.1 | | 0.1 | 0.1 | V | |
| | | 5.5V | | 0.001 | 0.1 | | 0.1 | 0.1 | | |
| | I _{OL} = 24 mA | 4.5V | | | 0.36 | | 0.5 | 0.44 | | |
| | | 5.5V | | | 0.36 | | 0.5 | 0.44 | | |
| | I _{OL} = 50 mA ⁽¹⁾ | 5.5V | | | | | 1.65 | | | |
| I _{OL} = 75 mA ⁽¹⁾ | 5.5V | | | | | | 1.65 | | | |
| I _I | V _I = V _{CC} or GND | 5.5V | | | ±0.1 | | ±1 | ±1 | μA | |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5V | | | 2 | | 40 | 20 | μA | |
| ΔI _{CC} ⁽²⁾ | One input at 3.4 V, Other inputs at GND or V _{CC} | 5.5 V | | 0.6 | | | 1.6 | 1.5 | mA | |
| C _i | V _I = V _{CC} or GND | 5V | | 2.6 | | | | | pF | |

(1) Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

(2) This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

4.5 Switching Characteristics

over recommended operating free-air temperature range, V_{CC} = 5V ± 0.5V (unless otherwise noted) (see [Load Circuit and Voltage Waveforms](#))

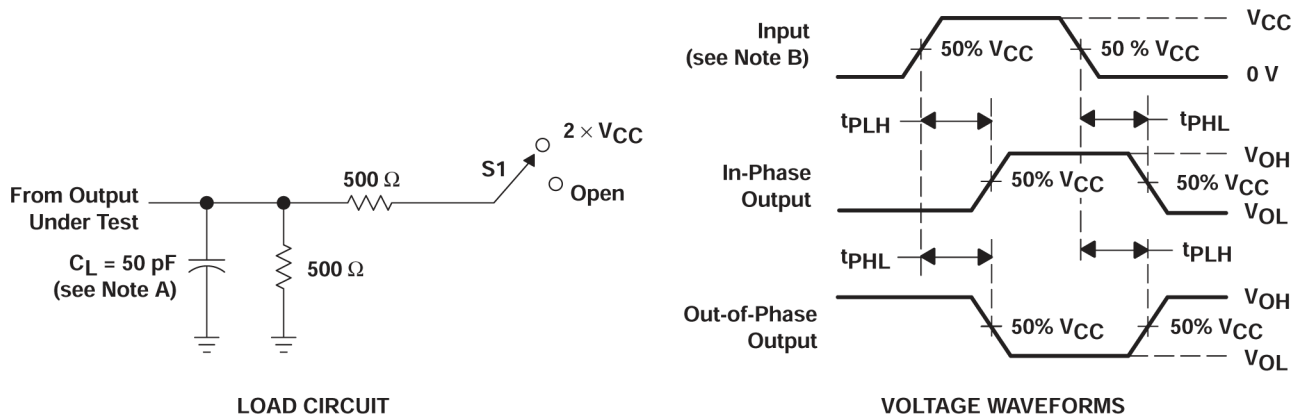
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | T _A = 25°C | | | SN54ACT11 | | SN74ACT11 | | UNIT |
|------------------|--------------|-------------|-----------------------|-----|-----|-----------|------|-----------|------|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| t _{PLH} | A, B, or C | Y | 1.5 | 6 | 9.5 | 1 | 10.5 | 1 | 10.5 | ns |
| t _{PHL} | | | 1.5 | 6 | 9.5 | 1 | 10.5 | 1 | 10.5 | |

4.6 Operating Characteristics

V_{CC} = 5 V, T_A = 25°C

| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|-----------------|-----------------------------------|-----|------|
| C _{pd} | C _L = 50 pF, f = 1 MHz | 20 | pF |

5 Parameter Measurement Information



- A. C_L includes probe and jig capacitance.
- B. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 5-1. Load Circuit and Voltage Waveforms

| TEST | S1 |
|-------------------|------|
| t_{PLH}/t_{PHL} | Open |

6 Detailed Description

6.1 Functional Block Diagram

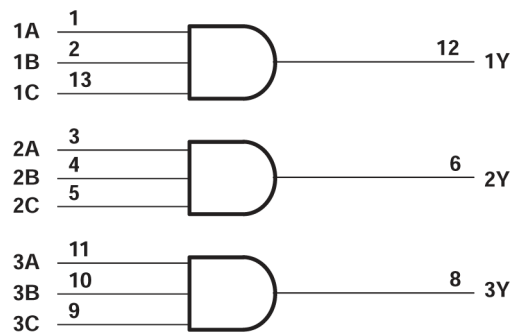


Figure 6-1. Logic Diagram, Each Gate (Positive Logic)

Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

6.2 Device Functional Modes

Table 6-1. Function Table (Each Gate)

| INPUTS | | | OUTPUT |
|--------|---|---|--------|
| A | B | C | Y |
| H | H | H | H |
| L | X | X | L |
| X | L | X | L |
| X | X | L | L |

7 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

7.1 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#). Each V_{CC} terminal should have a bypass capacitor to prevent power disturbance. A 0.1- μ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

7.2 Layout

7.2.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

8 Device and Documentation Support

8.1 Documentation Support (Analog)

8.1.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|-----------|----------------------------|----------------------------|----------------------------|----------------------------|----------------------------|
| SN54ACT11 | Click here | Click here | Click here | Click here | Click here |
| SN74ACT11 | Click here | Click here | Click here | Click here | Click here |

8.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

8.3 Support Resources

[TI E2E™ support forums](#) are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

8.4 Trademarks

TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

8.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.6 Glossary

[TI Glossary](#) This glossary lists and explains terms, acronyms, and definitions.

9 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision C (October 2003) to Revision D (July 2024) | Page |
|---|------|
| • Added <i>Device Information</i> table, <i>Pin Functions</i> table, <i>Thermal Information</i> table, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section | 1 |
| • Updated RθJA values: D = 86 to 119.9, PW = 113 to 145.7, all values in °C/W..... | 4 |

10 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|------------------|--------------------------------------|----------------------|--------------|-------------------------------------|-------------------------|
| 5962-9077201Q2A | ACTIVE | LCCC | FK | 20 | 55 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9077201Q2A SNJ54ACT 11FK | Samples |
| 5962-9077201QDA | ACTIVE | CFP | W | 14 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9077201QD A SNJ54ACT11W | Samples |
| SN74ACT11D | OBSOLETE | SOIC | D | 14 | | TBD | Call TI | Call TI | -40 to 85 | ACT11 | |
| SN74ACT11DBR | ACTIVE | SSOP | DB | 14 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AD11 | Samples |
| SN74ACT11DR | ACTIVE | SOIC | D | 14 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ACT11 | Samples |
| SN74ACT11DRG4 | ACTIVE | SOIC | D | 14 | 2500 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | ACT11 | Samples |
| SN74ACT11N | ACTIVE | PDIP | N | 14 | 25 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74ACT11N | Samples |
| SN74ACT11PW | OBSOLETE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -40 to 85 | AD11 | |
| SN74ACT11PWR | ACTIVE | TSSOP | PW | 14 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AD11 | Samples |
| SNJ54ACT11FK | ACTIVE | LCCC | FK | 20 | 55 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9077201Q2A SNJ54ACT 11FK | Samples |
| SNJ54ACT11W | ACTIVE | CFP | W | 14 | 25 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9077201QD A SNJ54ACT11W | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ACT11, SN74ACT11 :

- Catalog : [SN74ACT11](#)
- Military : [SN54ACT11](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|--------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74ACT11DBR | SSOP | DB | 14 | 2000 | 330.0 | 16.4 | 8.35 | 6.6 | 2.4 | 12.0 | 16.0 | Q1 |
| SN74ACT11DR | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74ACT11PWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|--------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74ACT11DBR | SSOP | DB | 14 | 2000 | 356.0 | 356.0 | 35.0 |
| SN74ACT11DR | SOIC | D | 14 | 2500 | 356.0 | 356.0 | 35.0 |
| SN74ACT11PWR | TSSOP | PW | 14 | 2000 | 356.0 | 356.0 | 35.0 |

TUBE


*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (μm) | B (mm) |
|-----------------|--------------|--------------|------|-----|--------|--------|--------|--------|
| 5962-9077201Q2A | FK | LCCC | 20 | 55 | 506.98 | 12.06 | 2030 | NA |
| 5962-9077201QDA | W | CFP | 14 | 25 | 506.98 | 26.16 | 6220 | NA |
| SN74ACT11N | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SN74ACT11N | N | PDIP | 14 | 25 | 506 | 13.97 | 11230 | 4.32 |
| SNJ54ACT11FK | FK | LCCC | 20 | 55 | 506.98 | 12.06 | 2030 | NA |
| SNJ54ACT11W | W | CFP | 14 | 25 | 506.98 | 26.16 | 6220 | NA |

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only.
 - E. Falls within MIL STD 1835 GDFP1-F14

DB0014A



PACKAGE OUTLINE

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

EXAMPLE BOARD LAYOUT

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



4220762/A 05/2024

NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DB0014A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220762/A 05/2024

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

GENERIC PACKAGE VIEW

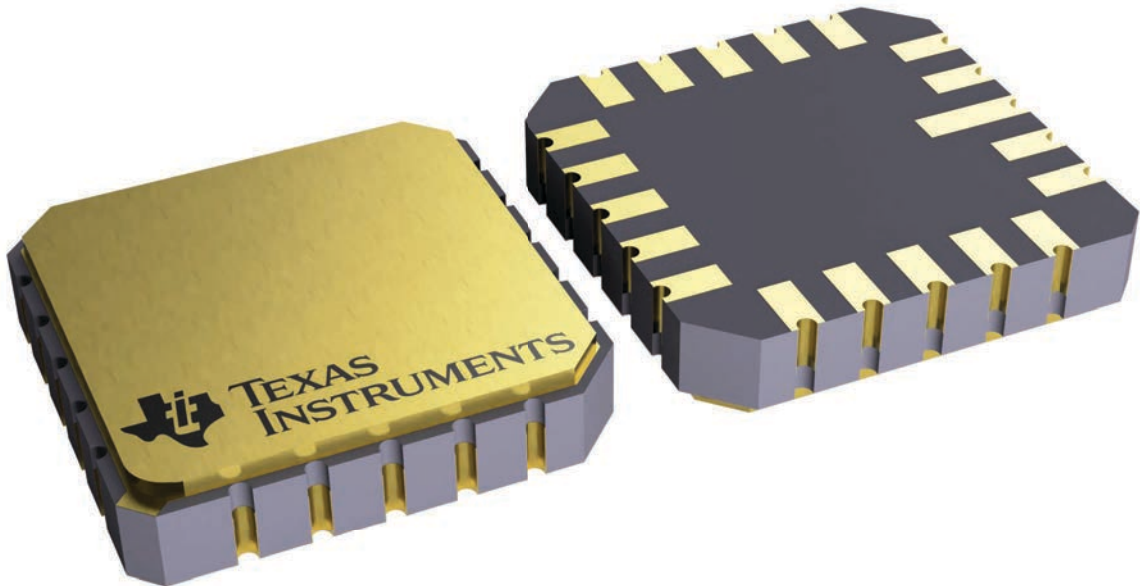
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.





4229370VA\

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - $\triangle D$ The 20 pin end lead shoulder width is a vendor option, either half or full width.

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